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**THIS SPEC IS OBSOLETE**

Spec No: 001-53145

Spec Title: CY2XF23 HIGH PERFORMANCE LVDS OSCILLATOR  
WITH FREQUENCY MARGINING - I2C CONTROL

Sunset Owner: Hiromu Takehara (xht)

Replaced by: NONE

# High Performance LVDS Oscillator with Frequency Margining - I<sup>2</sup>C Control

## Features

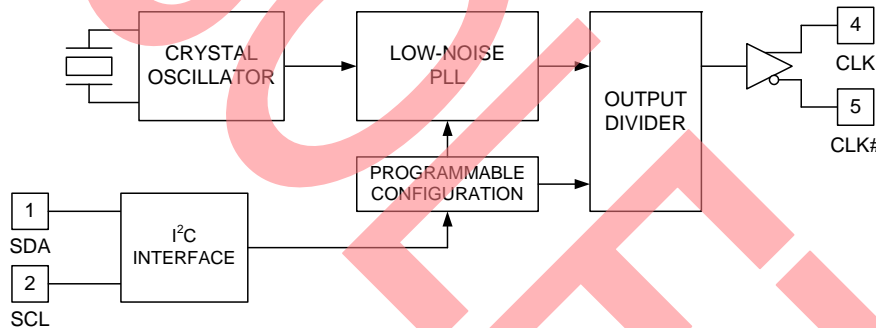
- Low jitter crystal oscillator (XO)
- Less than 1 ps typical root mean square (RMS) phase jitter
- Low-voltage differential signaling (LVDS) output
- Output frequency from 50 MHz to 690 MHz
- Frequency margining through I<sup>2</sup>C bus
- Factory-configured or field-programmable
- Integrated phase-locked loop (PLL)
- Pb-free package: 5.0 × 3.2 mm leadless chip carrier (LCC)
- Supply voltage: 3.3 V or 2.5 V
- Commercial and industrial temperature ranges

## Functional Description

The CY2XF23 is a high-performance and high-frequency XO. It uses a Cypress proprietary low-noise PLL to synthesize the frequency from an integrated crystal. The output frequency can be changed using the I<sup>2</sup>C bus serial interface, allowing easy frequency margin testing in applications.

The CY2XF23 is available as a factory-configured device or as a field-programmable device. Factory configured devices are configured for general use (see “Standard and Application-Specific Factory Configurations” on page 4) or they can be customer specific.

## Logic Block Diagram

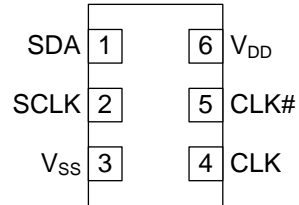


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## Pinouts

Figure 1. Pin Diagram – 6-pin Ceramic LCC



## Pin Definitions

6-pin Ceramic LCC

| Pin  | Name            | I/O Type    | Description                    |
|------|-----------------|-------------|--------------------------------|
| 1    | SDA             | I/O         | I <sup>2</sup> C serial data   |
| 2    | SCLK            | CMOS input  | I <sup>2</sup> C serial clock  |
| 4, 5 | CLK, CLK#       | LVDS output | Differential output clock      |
| 6    | V <sub>DD</sub> | Power       | Supply voltage: 2.5 V or 3.3 V |
| 3    | V <sub>SS</sub> | Power       | Ground                         |

## Standard and Application-Specific Factory Configurations

| Part Number    | Output Frequency     | Frequency Word | RMS Phase Jitter (Random) |                  |
|----------------|----------------------|----------------|---------------------------|------------------|
|                |                      |                | Offset Range              | Jitter (Typical) |
| CY2XF23LXC001T | 100.00 MHz (default) | 0              | 637 kHz to 10 MHz         | 0.52 ps          |
|                | 95.00 MHz            | 1              | 637 kHz to 10 MHz         | –                |
|                | 103.000007 MHz       | 2              | 637 kHz to 10 MHz         | –                |
|                | 104.999993 MHz       | 3              | 637 kHz to 10 MHz         | –                |

### Functional Description

The CY2XF23 is a PLL-based high-performance clock generator. It uses an internal crystal oscillator as a reference, and outputs one differential LVDS clock. It has an I<sup>2</sup>C bus serial interface<sup>[1]</sup>, which is used to change the output frequency.

The CY2XF23 comes configured for four different frequencies. At power-on, the four configurations are transparently loaded into an internal volatile memory which, in turn, controls the PLL. The user can switch between the four frequencies through the I<sup>2</sup>C bus. The user can also configure the CY2XF23 with new output frequencies by shifting new data into the internal memory.

Frequency margining is a common application for this feature. One frequency is used for the standard operating mode of the device, while additional frequencies are available for margin testing, either during product development or in-system manufacturing test.

Note that all configuration changes made using I<sup>2</sup>C are temporary and are lost when power is removed from the device. At power-on, the device returns to its original state.

The configuration for a particular frequency is stored in a 6-byte block of memory, known as a word. The CY2XF23 has four such words, labeled 'Frequency Word 0' through 'Frequency Word 3'. An additional register byte contains a 2-bit field, which selects one of the four frequency words. By writing to this select byte, the user can switch back and forth between the four programmed frequencies. The select byte can be configured to select any of the four frequency words at power-on.

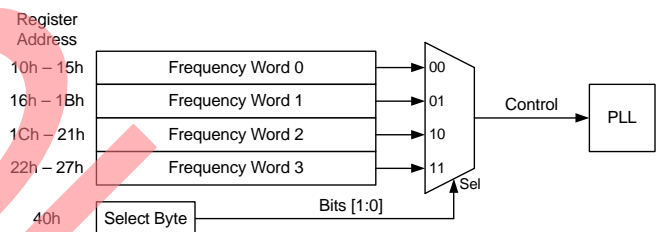
When changing the output frequency, the frequency transition is not guaranteed to be smooth. There can be frequency excursions beyond the start frequency and the new frequency.

Glitches and runt pulses are possible, and time must be allowed for the PLL to re-lock.

If more than four frequencies are needed, the I<sup>2</sup>C bus can be used to change any of the four frequency words. When writing frequency words through I<sup>2</sup>C, the users should not change the currently selected word. Instead, write one of the three unselected words before changing the select byte to select that new word.

Figure 2 shows how the frequency words are arranged and selected.

Figure 2. Frequency Words



### Configuration Software

Cypress provides CyClockWizard™ software that enables the users to create data values for shifting into the frequency words. This software is required because the algorithm is too complicated to be described here.

The user specifies the output frequency. The software then calculates the bit stream for up to four frequency words, as outlined by the register addresses for each word seen in Figure 2.

**Note**

1. The serial interface is I<sup>2</sup>C Bus compliant, with the following exceptions: SDA input leakage current, SDA input capacitance, SDA and SCLK are clamped to V<sub>DD</sub>, setup time, and output hold time.

## Programming Description

The CY2XF23 is a programmable device. Before being used in an application, it must be programmed with the output frequencies and other variables described in [Programming Variables on page 5](#). Two different device types are available, each with its own programming flow. They are described in the following sections.

### Field-Programmable CY2XF23F

Field-programmable devices are shipped unprogrammed and must be programmed before being installed on a printed circuit board (PCB). Customers use [CyClockWizard™](#) software to specify the device configuration and generate a joint electron devices engineering council (JEDEC - extension .jed) programming file. Programming of samples and prototype quantities is available using the [CyClockWizard](#) software along with a [CY3675-CLKMAKER1 CyClockMaker Clock Programmer Kit](#) with a [CY3675-LCC6A socket adapter](#). Cypress's value added distribution partners also provide programming services. Field programmable devices are designated with an 'F' in the part number. They are intended for quick prototyping and inventory reduction. The software and programmer kit hardware can be downloaded from [www.cypress.com](http://www.cypress.com) by clicking the hyperlinks above.

### Factory-Configured CY2XF23

For ready-to-use devices, the CY2XF23 is available with no field programming required. Pre-configured devices (see ["Standard and Application-Specific Factory Configurations"](#) on page 4) are available for samples or orders, or a request for a custom configuration can be made. All requests are submitted to the local Cypress Field Application Engineer (FAE) or sales representative. After the request is processed, the user receives a new part number, samples, and datasheet with the programmed values. This part number is used for additional sample requests and production orders. The CY2XF23 is one-time programmable (OTP).

## Programming Variables

### Output Frequencies

The CY2XF23 is programmed with up to four independent output frequencies, which are then selected using the I<sup>2</sup>C interface. The device can synthesize frequencies to a resolution of 1 part per million (ppm), but the actual accuracy of the output frequency is limited by the accuracy of the integrated reference crystal.

The CY2XF23 has an output frequency range of 50 MHz to 690 MHz, but the range is not continuous. The CY2XF23 cannot generate frequencies in the ranges of 521 MHz to 529 MHz and 596 MHz to 617 MHz.

### Industrial versus Commercial Device Performance

Industrial and commercial devices have different internal crystals. They have a potentially significant impact on performance levels for applications requiring the lowest possible phase noise. [CyClockWizard](#) software allows the user to select between and view the expected performance of both options.

Table 1. Device Programming Variables

| Variable                                     |
|----------------------------------------------|
| Output frequency 0                           |
| Output frequency 1                           |
| Output frequency 2                           |
| Output frequency 3                           |
| Temperature range (commercial or industrial) |

## Memory Map

Five fields can be written via the I<sup>2</sup>C bus. Four frequency words define the output frequency. As shown in [Table 2](#), each of these words is a 6-byte field. When writing to a frequency word, all six bytes should be written. They may be written either as individual byte writes, or as a block write. The currently selected frequency word should not be written to. All four words are symmetrical, meaning that a 6-byte value that is valid for one word is also valid for any of the other words, and produces the same frequency.

The fifth field is the select byte, located at byte address 40h. The value written into the two least significant bits determines the active frequency word. The other bits of the byte are reserved and must be written with the values indicated in the table. Users should never write to any address other than the 25 bytes described here.

Table 2. Frequency Words

| Frequency Word | Byte Addresses (hex) | Word Select (Select Byte 40h) |
|----------------|----------------------|-------------------------------|
| 0              | 10h to 15h           | 00                            |
| 1              | 16h to 1Bh           | 01                            |
| 2              | 1Ch to 21h           | 10                            |
| 3              | 22h to 27h           | 11                            |

Table 3. Register 40h: Select Byte

| Bits | Default Value (binary) | Name        | Description                                                                                                                               |
|------|------------------------|-------------|-------------------------------------------------------------------------------------------------------------------------------------------|
| 7:2  | 000000                 | Reserved    | Reserved. Always write this value.                                                                                                        |
| 1:0  | User-defined           | Word select | Selects the Frequency Word to determine the output frequency. 00 selects Word 0; 01 selects Word 1; 10 selects Word 2; 11 selects Word 3. |

## Serial Interface Protocol and Timing

The CY2XF23 uses pins SDA and SCLK for an I<sup>2</sup>C bus that operates up to 100 kbits/sec in read or write mode. The CY2XF23 is always a slave on this bus, meaning that it never initiates a bus transaction. The basic write protocol is as follows:

Start Bit; 7-bit Device Address (DA); R $\bar{W}$  Bit; Slave Clock Acknowledge (ACK); 8-bit Memory Address (MA); ACK; 8-bit Data; ACK; 8-bit Data in MA+1 if desired; ACK; 8-bit Data in MA+2; ACK; and so on, until STOP Bit. The basic serial format is illustrated in [Figure 4 on page 7](#).

## Device Address

The device I<sup>2</sup>C address is a 7-bit value. The default I<sup>2</sup>C address, which appears in [CyClockWizard](#) is 69H, which can be changed to any other value while generating configuration using [CyClockWizard](#). Note that the Field Programmable (unprogrammed<sup>[2]</sup>) devices has default address as 59H.

## Data Valid

Data is valid when the clock is HIGH, and may only be transitioned when the clock is LOW as illustrated in [Figure 5 on page 7](#).

## Data Frame

Every new data frame is indicated by a start and stop sequence, as illustrated in [Figure 6 on page 8](#).

**START Sequence** - Start frame is indicated by SDA going LOW when SCLK is HIGH. Every time a start signal is given, the next 8-bit data must be the device address (seven bits) and a R/W bit, followed by register address (eight bits) and register data (eight bits).

**STOP Sequence** - Stop frame is indicated by SDA going HIGH when SCLK is HIGH. A stop frame frees the bus for writing to another part on the same bus or writing to another random register address.

## Acknowledge Pulse

During write mode, the CY2XF23 responds with an Acknowledge (ACK) pulse after every eight bits. This is accomplished by pulling the SDA line LOW during the N<sup>th</sup> clock cycle as illustrated in [Figure 7 on page 8](#). (N = the number of bytes transmitted). After the data packet is sent during read mode, the master generates the acknowledge.

## Write Operations

### Writing Individual Bytes

A valid write operation must have a full 8-bit register address after the device address word from the master, which is followed by an acknowledge bit from the slave (SDA = 0/LOW). The next eight bits must contain the data word intended for storage. After the data word is received, the slave responds with another acknowledge bit (SDA = 0/LOW), and the master must end the write sequence with a STOP condition.

### Writing Multiple Bytes

To write more than one byte at a time, the master does not end the write sequence with a stop condition. Instead, the master can send multiple contiguous bytes of data to be stored. After each

byte, the slave responds with an acknowledge bit, just like after the first byte, and accepts data until the acknowledge bit is responded to by the STOP condition. When receiving multiple bytes, the CY2XF23 internally increments the register address.

## Read Operations

Read operations are initiated the same way as write operations except that the R/W bit of the slave address is set to '1' (HIGH). There are three basic read operations: current address read, random read, and sequential read.

### Current Address Read

The CY2XF23 has an onboard address counter that retains 1 more than the address of the last word access. If the last word written or read was word 'n', then a current address read operation would return the value stored in location 'n+1'. When the CY2XF23 receives the slave address with the R/W bit set to a '1', the CY2XF23 issues an acknowledge and transmits the 8-bit word. The master device does not acknowledge the transfer, but does generate a STOP condition, which causes the CY2XF23 to stop transmission.

### Random Read

Through random read operations, the master may access any memory location. To perform this type of read operation, first the word address must be set. This is accomplished by sending the address to the CY2XF23 as part of a write operation. After the word address is sent, the master generates a START condition following the acknowledge. This terminates the write operation before any data is stored in the address, but not before the internal address pointer is set. Next the master reissues the control byte with the R/W byte set to '1'. The CY2XF23 then issues an acknowledge and transmits the 8-bit word. The master device does not acknowledge the transfer, but does generate a STOP condition which causes the CY2XF23 to stop transmission.

### Sequential Read

Sequential read operations follow the same process as random reads except that the master issues an acknowledge instead of a STOP condition after transmission of the first 8-bit data word. This action results in an incrementing of the internal address pointer, and subsequently output of the next 8-bit data word. By continuing to issue acknowledges instead of STOP conditions, the master may serially read the entire contents of the slave device memory. When the internal address pointer points to the FFh register, after the next increment, the pointer will point to the 00h register.

#### Note

- Field programmable devices are shipped unprogrammed and must be programmed before being installed on a PCB. An unprogrammed device will output the crystal frequency of the integrated crystal (25 MHz for commercial and 38.8 MHz for industrial).



Figure 3. Data Transfer Sequence on the Serial Bus

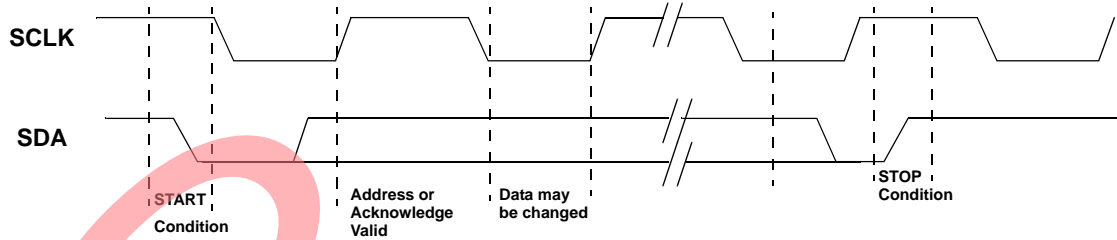


Figure 4. Data Frame Architecture

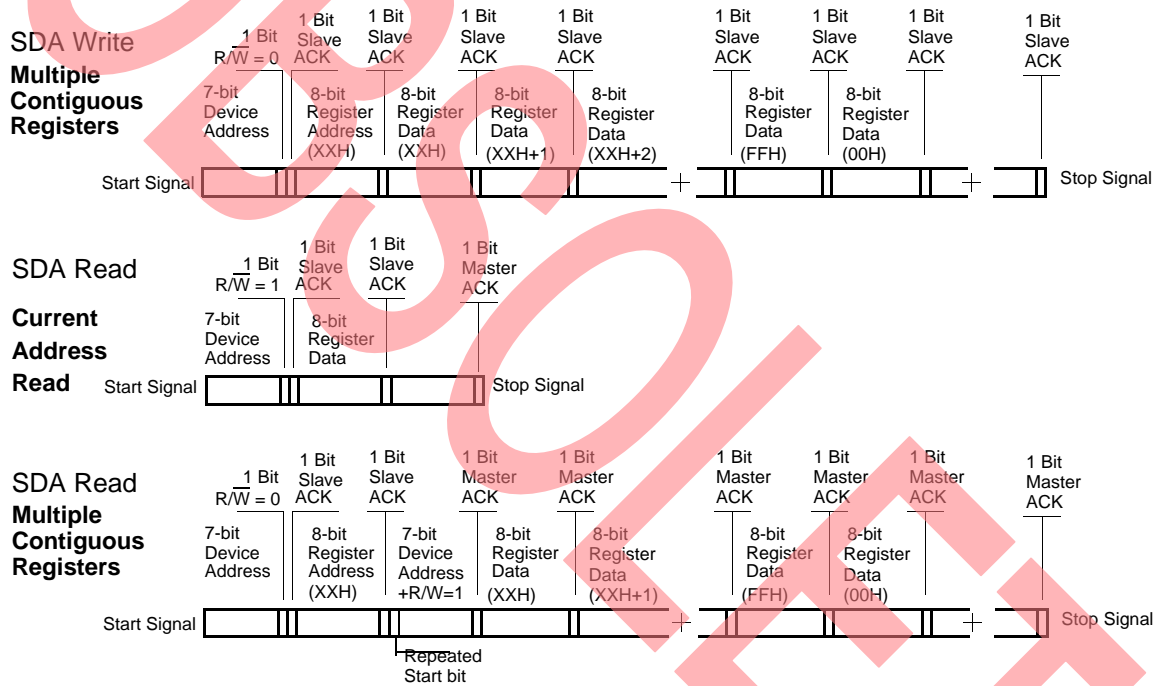


Figure 5. Data Valid and Data Transition Periods

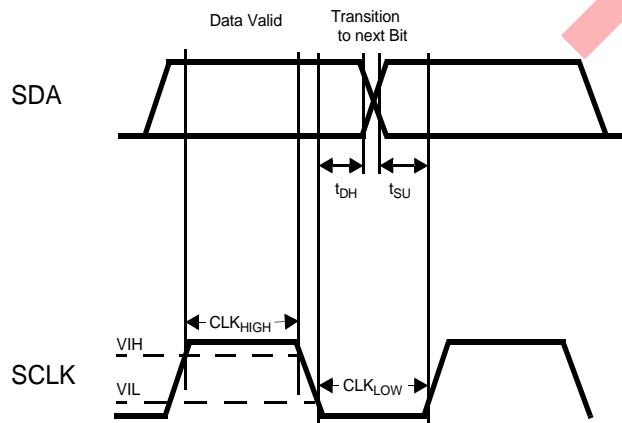


Figure 6. Start and Stop Frame

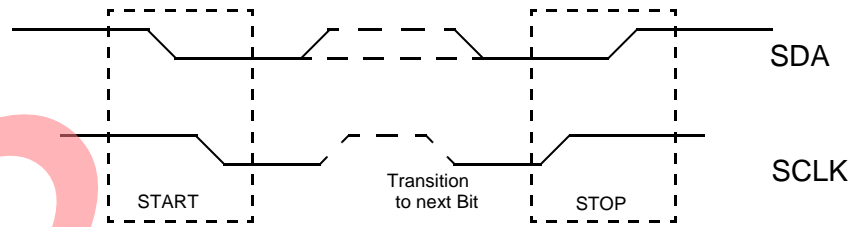
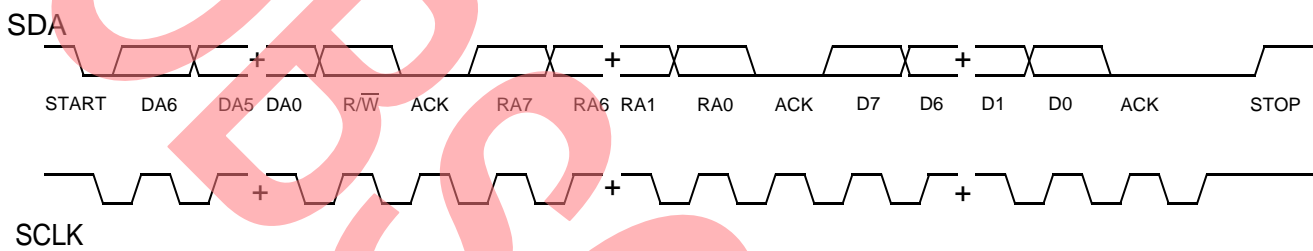


Figure 7. Frame Format (Device Address, R/W, Register Address, Register Data)



### Absolute Maximum Conditions

| Parameter                      | Description                                                     | Condition                   | Min  | Max                   | Unit |
|--------------------------------|-----------------------------------------------------------------|-----------------------------|------|-----------------------|------|
| V <sub>DD</sub>                | Supply voltage                                                  |                             | -0.5 | 4.4                   | V    |
| V <sub>IN</sub> <sup>[3]</sup> | Input voltage, DC                                               | Relative to V <sub>SS</sub> | -0.5 | V <sub>DD</sub> + 0.5 | V    |
| T <sub>S</sub>                 | Temperature, storage                                            | Non Operating               | -55  | 135                   | °C   |
| T <sub>J</sub>                 | Temperature, junction                                           |                             | -40  | 135                   | °C   |
| ESD <sub>HBM</sub>             | Electrostatic discharge (ESD) protection human body model (HBM) | JEDEC Std 22-A114-B         | 2000 | -                     | V    |
| Θ <sub>JA</sub> <sup>[4]</sup> | Thermal resistance, junction to ambient                         | 0 m/s airflow               |      | 64                    | °C/W |

### Operating Conditions

| Parameter       | Description                                                                                    | Min   | Typ | Max   | Unit |
|-----------------|------------------------------------------------------------------------------------------------|-------|-----|-------|------|
| V <sub>DD</sub> | 3.3-V supply voltage range                                                                     | 3.135 | 3.3 | 3.465 | V    |
|                 | 2.5-V supply voltage range                                                                     | 2.375 | 2.5 | 2.625 | V    |
| T <sub>PU</sub> | Power-up time for V <sub>DD</sub> to reach minimum specified voltage (power ramp is monotonic) | 0.05  | -   | 500   | ms   |
| T <sub>A</sub>  | Ambient temperature (commercial)                                                               | 0     | -   | 70    | °C   |
|                 | Ambient temperature (industrial)                                                               | -40   | -   | 85    | °C   |

#### Notes

- The voltage on any input or I/O pin cannot exceed the power pin during power-up.
- Simulated. The board is derived from the JEDEC multilayer standard. It measures 76 × 114 × 1.6 mm and has 4-layers of copper (2/1/1/2 oz.). The internal layers are 100% copper planes, while the top and bottom layers have 50% metalization. No vias are included in the model.

**DC Electrical Characteristics**

| Parameter                       | Description                                                   | Condition                                                                                               | Min                   | Typ | Max                   | Unit |
|---------------------------------|---------------------------------------------------------------|---------------------------------------------------------------------------------------------------------|-----------------------|-----|-----------------------|------|
| I <sub>DD</sub> <sup>[5]</sup>  | Operating supply current                                      | V <sub>DD</sub> = 3.465 V, CLK = 150 MHz, output terminated                                             | –                     | –   | 120                   | mA   |
|                                 |                                                               | V <sub>DD</sub> = 2.625 V, CLK = 150 MHz, output terminated                                             | –                     | –   | 115                   | mA   |
| V <sub>OD</sub>                 | LVDS differential output voltage                              | V <sub>DD</sub> = 3.3 V or 2.5 V, defined in Figure 8 on page 11 as terminated in Figure 13 on page 12. | 247                   | –   | 454                   | mV   |
| ΔV <sub>OD</sub>                | Change in V <sub>OD</sub> between complementary output states | V <sub>DD</sub> = 3.3 V or 2.5 V, defined in Figure 8 on page 11 as terminated in Figure 13 on page 12. | –                     | –   | 50                    | mV   |
| V <sub>OS</sub>                 | LVDS offset output voltage                                    | V <sub>DD</sub> = 3.3 V or 2.5 V, defined in Figure 9 on page 11 as terminated in Figure 13 on page 12. | 1.125                 | –   | 1.375                 | V    |
| ΔV <sub>OS</sub>                | Change in V <sub>OS</sub> between complementary output states | V <sub>DD</sub> = 3.3 V or 2.5 V, R <sub>TERM</sub> = 100 Ω between CLK and CLK#                        | –                     | –   | 50                    | mV   |
| V <sub>OLS</sub>                | Output low voltage (SDA)                                      | I <sub>OL</sub> = 4 mA                                                                                  | –                     | –   | 0.1 × V <sub>DD</sub> | V    |
| V <sub>IH</sub>                 | Input high voltage                                            |                                                                                                         | 0.7 × V <sub>DD</sub> | –   | –                     | V    |
| V <sub>IL</sub>                 | Input low voltage                                             |                                                                                                         | –                     | –   | 0.3 × V <sub>DD</sub> | V    |
| I <sub>IH0</sub>                | Input high current (SDA)                                      | Input = V <sub>DD</sub>                                                                                 | –                     | –   | 115                   | μA   |
| I <sub>IH1</sub>                | Input high current (SCLK)                                     | Input = V <sub>DD</sub>                                                                                 | –                     | –   | 10                    | μA   |
| I <sub>IL0</sub>                | Input low current (SDA)                                       | Input = V <sub>SS</sub>                                                                                 | –50                   | –   | –                     | μA   |
| I <sub>IL1</sub>                | Input low current (SCLK)                                      | Input = V <sub>SS</sub>                                                                                 | –20                   | –   | –                     | μA   |
| C <sub>IN0</sub> <sup>[6]</sup> | Input capacitance (SDA)                                       |                                                                                                         | –                     | 15  | –                     | pF   |
| C <sub>IN1</sub> <sup>[6]</sup> | Input capacitance (SCLK)                                      |                                                                                                         | –                     | 4   | –                     | pF   |

**Notes**

5. I<sub>DD</sub> includes –4 mA of current that is dissipated externally in the output termination resistors.
6. Not 100% tested, guaranteed by design and characterization.

**AC Electrical Characteristics<sup>[7]</sup>**

| Parameter                       | Description                                            | Condition                                                                                                                        | Min         | Typ  | Max | Unit |
|---------------------------------|--------------------------------------------------------|----------------------------------------------------------------------------------------------------------------------------------|-------------|------|-----|------|
| F <sub>OUT</sub>                | Output frequency <sup>[8]</sup>                        |                                                                                                                                  | 50          | –    | 690 | MHz  |
| FSC                             | Frequency stability, commercial devices <sup>[9]</sup> | V <sub>DD</sub> = min to max, T <sub>A</sub> = 0 °C to 70 °C                                                                     | –           | –    | ±35 | ppm  |
| FSI                             | Frequency stability, industrial devices <sup>[9]</sup> | V <sub>DD</sub> = min to max, T <sub>A</sub> = –40 °C to 85 °C                                                                   | –           | –    | ±55 | ppm  |
| AG                              | Aging, 10 years                                        |                                                                                                                                  | –           | –    | ±15 | ppm  |
| T <sub>DC</sub>                 | Output duty cycle                                      | F ≤ 450 MHz, measured at zero crossing                                                                                           | 45          | 50   | 55  | %    |
|                                 |                                                        | F > 450 MHz, measured at zero crossing                                                                                           | 40          | 50   | 60  | %    |
| T <sub>R</sub> , T <sub>F</sub> | Output rise and fall time                              | 20% and 80% of full output swing                                                                                                 | –           | 0.35 | 1.0 | ns   |
| T <sub>LOCK</sub>               | Startup time                                           | Time for CLK to reach valid frequency measured from the time when V <sub>DD</sub> = V <sub>DD</sub> (min.)                       | –           | –    | 5   | ms   |
| T <sub>LSE</sub>                | Relock time                                            | Time for CLK to reach valid frequency from serial bus change to select bits in register 40h, measured from I <sup>2</sup> C STOP | –           | –    | 1   | ms   |
| T <sub>Jitter(φ)</sub>          | RMS phase jitter (random)                              | F <sub>OUT</sub> = 106.25 MHz (12 kHz to 20 MHz)                                                                                 | –           | 1    | –   | ps   |
|                                 |                                                        | Pre-defined factory configurations <sup>[10]</sup>                                                                               | See Note 10 |      |     | ps   |

**I<sup>2</sup>C Bus Timing Specifications<sup>[7]</sup>**

| Parameter           | Description                                            | Min  | Max | Unit |
|---------------------|--------------------------------------------------------|------|-----|------|
| f <sub>SCLK</sub>   | SCLK frequency                                         | –    | 100 | kHz  |
| t <sub>HD:STA</sub> | Start mode time from SDA LOW to SCLK LOW               | 4    | –   | μs   |
| t <sub>LOW</sub>    | SCLK LOW period                                        | 4.7  | –   | μs   |
| t <sub>HIGH</sub>   | SCLK HIGH period                                       | 4    | –   | μs   |
| t <sub>SU:DAT</sub> | Input data setup (SDA transition to SCLK rising edge)  | 1000 | –   | ns   |
| t <sub>HD:DAT</sub> | Input data hold (SCLK falling edge to SDA transition)  | 0    | –   | ns   |
| t <sub>HD:DO</sub>  | Output data hold (SCLK falling edge to SDA transition) | 200  | –   | ns   |
| t <sub>SR</sub>     | Rise time of SCLK and SDA                              | –    | 300 | ns   |
| t <sub>SF</sub>     | Fall time of SCLK and SDA                              | –    | 300 | ns   |
| t <sub>SU:STO</sub> | Stop mode time from SCLK HIGH to SDA HIGH              | 4    | –   | μs   |
| t <sub>BUF</sub>    | Stop mode to start mode                                | 4.7  | –   | μs   |

**Notes**

7. Not 100% tested, guaranteed by design and characterization.
8. This parameter is specified in CyClockWizard software.
9. Frequency stability is the maximum variation in frequency from F<sub>0</sub>. It includes initial accuracy, plus variation from temperature and supply voltage.
10. Typical phase noise specs for factory programmed devices are listed in the "Standard and Application-Specific Factory Configurations" on page 4.

Switching Waveforms

Figure 8. Output Voltage Swing

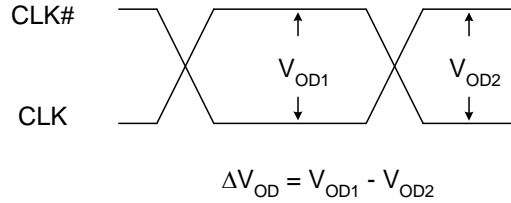


Figure 9. Output Offset Voltage

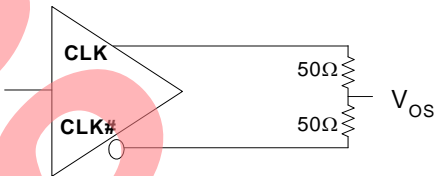


Figure 10. Duty Cycle Timing

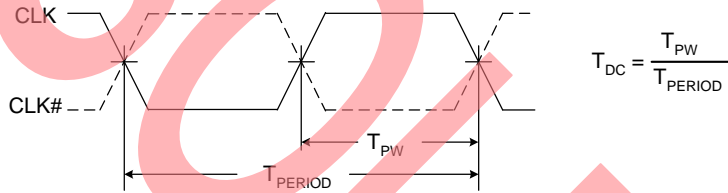


Figure 11. Output Rise and Fall Time

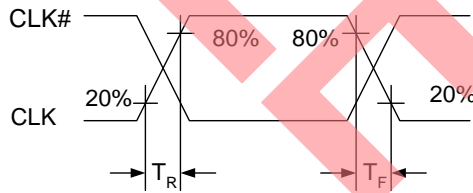
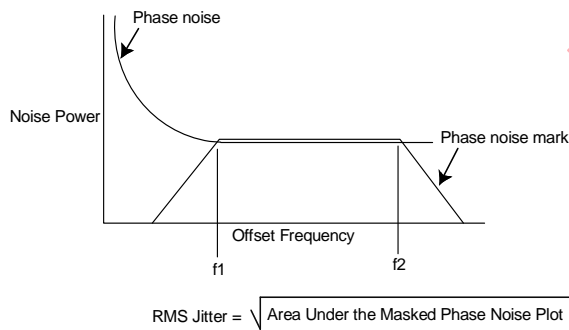
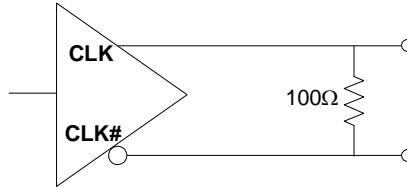


Figure 12. RMS Phase Jitter



## Termination Circuits

Figure 13. LVDS Termination



## Ordering Information

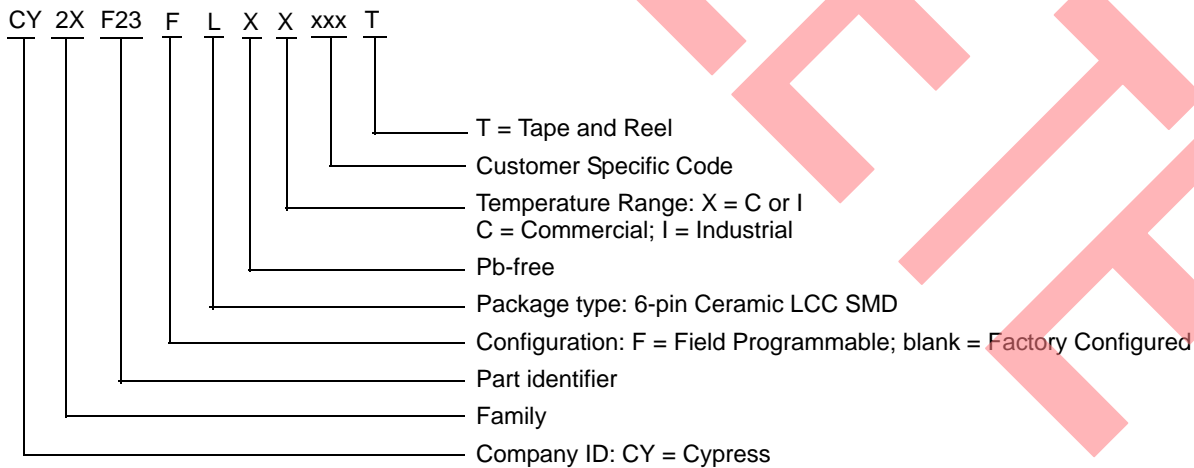
| Part Number                    | Configuration      | Package Description                                          | Product Flow                |
|--------------------------------|--------------------|--------------------------------------------------------------|-----------------------------|
| <b>Pb-free</b>                 |                    |                                                              |                             |
| CY2XF23FLXCT                   | Field-programmable | 6-pin ceramic LCC surface mount device (SMD) - tape and reel | Commercial, 0 °C to 70 °C   |
| CY2XF23FLXIT                   | Field-programmable | 6-pin ceramic LCC SMD - tape and reel                        | Industrial, -40 °C to 85 °C |
| CY2XF23LXC001T <sup>[11]</sup> | Factory-configured | 6-pin ceramic LCC SMD - tape and reel                        | Commercial, 0 °C to 70 °C   |

Some product offerings are factory-programmed customer-specific devices with customized part numbers. The [Possible Configurations](#) table shows the available device types, but not complete part numbers. Contact your local Cypress FAE or sales representative for more information.

## Possible Configurations

| Part Number <sup>[12]</sup> | Configuration      | Package Description                   | Product Flow                |
|-----------------------------|--------------------|---------------------------------------|-----------------------------|
| <b>Pb-free</b>              |                    |                                       |                             |
| CY2XF23LXCxxxT              | Factory-configured | 6-pin ceramic LCC SMD - tape and reel | Commercial, 0 °C to 70 °C   |
| CY2XF23LXIxxxT              | Factory-configured | 6-pin ceramic LCC SMD - tape and reel | Industrial, -40 °C to 85 °C |

## Ordering Code Definitions

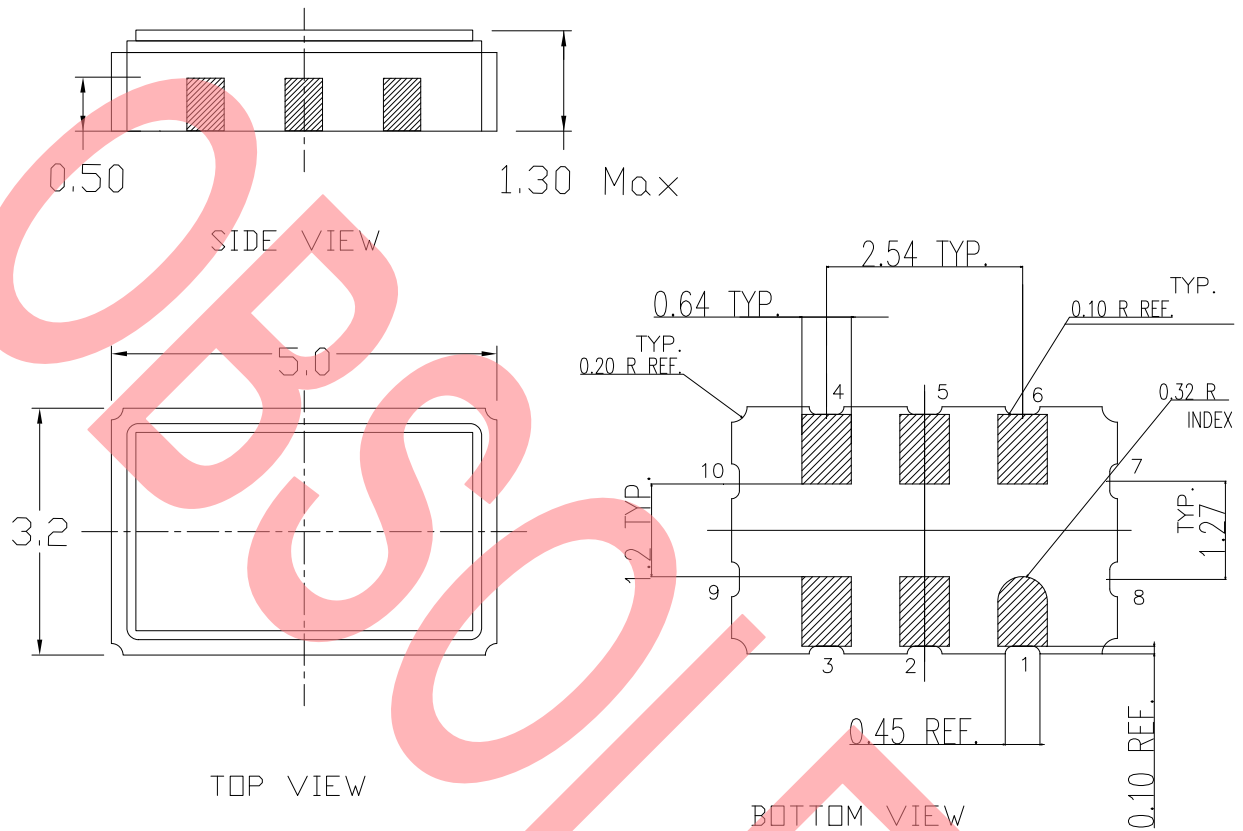


### Notes

11. Device configuration details are described in the "Standard and Application-Specific Factory Configurations" on page 4.
12. "xxx" indicates factory programmed parts based on customer specific configuration. For more details, contact your local Cypress FAE or Sales Representative.

Package Drawings and Dimensions

Figure 14. 6-pin 3.2 x 5.0 mm Ceramic LCC LZ06A



Dimensions in mm  
 Kyocera dwg ref KD-VA6432-A  
 Package Weight ~ 0.12 grams

001-10044 \*B

### Acronyms

| Acronym | Description                                |
|---------|--------------------------------------------|
| CMOS    | complementary metal oxide semiconductor    |
| ESD     | electrostatic discharge                    |
| FAE     | field application engineer                 |
| HBM     | human body model                           |
| I/O     | input/output                               |
| JEDEC   | joint electron devices engineering council |
| LCC     | leadless chip carrier                      |
| LVDS    | low-voltage differential signaling         |
| PCB     | printed circuit board                      |
| PLL     | phase-locked loop                          |
| RMS     | root mean square                           |
| XO      | crystal oscillator                         |

### Document Conventions

#### Units of Measure

| Symbol | Unit of Measure   |
|--------|-------------------|
| %      | percent           |
| °C     | degree Celsius    |
| kHz    | kilohertz         |
| mA     | milliamperere     |
| MHz    | megahertz         |
| mm     | millimeter        |
| ms     | millisecond       |
| mV     | millivolt         |
| ns     | nanosecond        |
| pF     | picofarad         |
| ppm    | parts per million |
| ps     | picosecond        |
| V      | volt              |
| Ω      | ohms              |
| W      | watt              |
| μA     | microampere       |
| μs     | microsecond       |



Document History Page

| Document Title: CY2XF23 High Performance LVDS Oscillator with Frequency Margining - I <sup>2</sup> C Control |         |                 |                 |                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                             |
|--------------------------------------------------------------------------------------------------------------|---------|-----------------|-----------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Document Number: 001-53145                                                                                   |         |                 |                 |                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                             |
| REV.                                                                                                         | ECN NO. | Orig. of Change | Submission Date | Description of Change                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                       |
| **                                                                                                           | 2704379 | KVM/PYRS        | 05/11/2009      | New data sheet                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                              |
| *A                                                                                                           | 2718898 | WWZ             | 06/15/09        | Minor ECN to post data sheet to external web                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                |
| *B                                                                                                           | 2764787 | KVM             | 09/18/09        | Change V <sub>OD</sub> limits from 250/450 mV to 247/454 mV<br>Add max limit for T <sub>R</sub> , T <sub>F</sub> : 1.0 ns<br>Change T <sub>LOCK</sub> max from 10 ms to 5 ms<br>Change T <sub>LSER</sub> max from 10 ms to 1 ms                                                                                                                                                                                                                                                                                                                                                                                                                                             |
| *C                                                                                                           | 2898585 | KVM             | 03/24/2010      | Updated Ordering Information<br>Added Possible COntfigurations<br>Updated Package Diagram                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                   |
| *D                                                                                                           | 2973338 | CXQ             | 07/08/2010      | Added <a href="#">Standard and Application-Specific Factory Configurations</a> table on page 2.<br>Added phase jitter specs for pre-defined configurations into the AC Electrical Specifications table (note 8 refers users to the new table on page 2 for typical specs).<br>Added CY2XF23LXI001T and CY2XF23LXI625T devices to the Ordering Information table and added note 9 to reference the configuration descriptions for each new device.<br>Changed all references to CyberClocksOnline software to CyClockWizard.<br>Removed section on phase noise vs jitter SW optimization.<br>Changed description of Word Select feature from default Word 0 to user-defined. |
| *E                                                                                                           | 3223673 | BASH            | 04/14/2011      | Changed status from Preliminary to Final.<br>Added <a href="#">Units of Measure</a> .<br>Updated in new template.                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                           |
| *F                                                                                                           | 3514321 | PURU            | 02/01/2012      | Updated <a href="#">Device Address</a> and added note 2.<br>Updated <a href="#">Package Drawings and Dimensions</a> .                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                       |
| *G                                                                                                           | 3847630 | AJU             | 12/20/2012      | Updated <a href="#">Standard and Application-Specific Factory Configurations</a> (Removed details of pruned part CY2XF23LXI625T).<br>Updated <a href="#">Ordering Information</a> (Updated part numbers).                                                                                                                                                                                                                                                                                                                                                                                                                                                                   |
| *H                                                                                                           | 4313180 | XHT             | 03/18/2014      | Obsolete spec                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                               |

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